4AK21

Silicon N-Channel Power MOS FET Array

HITACHI

Application

High speed power switching

Features

Low on-resistance

$$R_{DS(on)} = 0.09 , V_{GS} = 10 V, I_D = 4 A$$

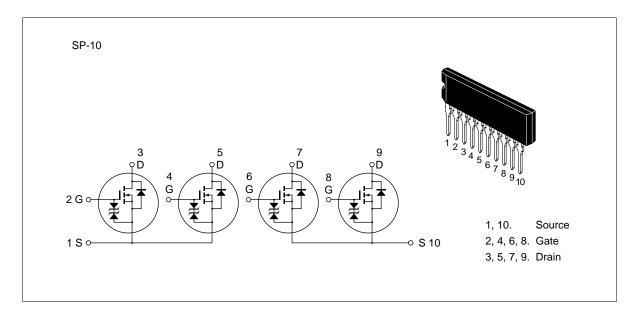
$$R_{DS(on)}$$
 0.12, V_{GS} = 4 V, I_D = 4 A

- Capable of 4 V gate drive
- Low drive current
- High speed switching
- High density mounting
- Suitable for motor driver, solenoid driver and lamp driver
- Discrete packaged devices of same die: 2SK1302, 2SK1307



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Outline



Absolute Maximum Ratings (Ta = 25°C) (1 Unit)

Item	Symbol	Rating	Unit
Drain to source voltage	V _{DSS}	100	V
Gate to source voltage	$V_{\sf GSS}$	±20	V
Drain current	I _D	8	A
Drain peak current	I _{D(pulse)} *1	32	A
Body to drain diode reverse drain current	I _{DR}	8	A
Channel dissipation	Pch (Tc = 25°C)*2	28	W
Channel dissipation	Pch*2	4	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. 4 devices operation

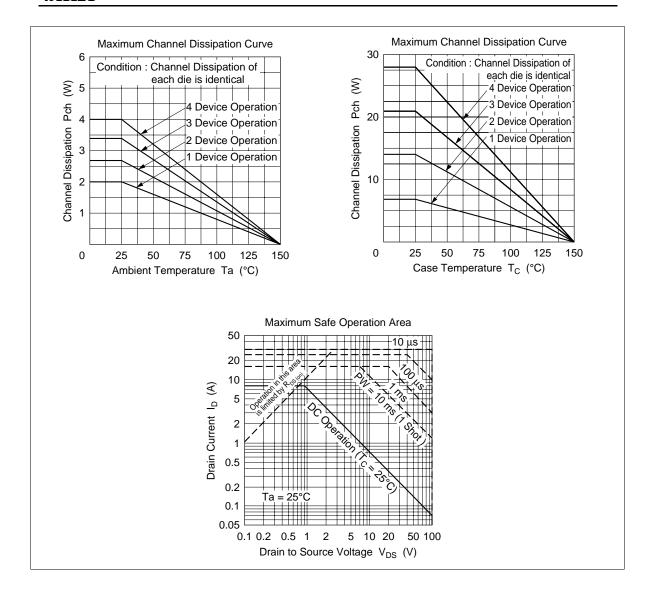
Electrical Characteristics (Ta = 25°C) (1 Unit)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	100	_	_	V	$I_{D} = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	250	μΑ	$V_{DS} = 80 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{\text{GS(off)}}$	1.0	_	2.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state	R _{DS(on)}	_	0.07	0.09	Ω	$I_D = 4 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
resistance		_	0.09	0.125	Ω	$I_D = 4 \text{ A}, V_{GS} = 4 \text{ V}^{*1}$
Forward transfer admittance	$ y_{fs} $	6.0	10.0	_	S	$I_D = 4 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance	Ciss	_	1300	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	540	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	160	_	pF	
Turn-on delay time	t _{d(on)}	_	12	_	ns	$I_D = 4 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	t _r	_	60	_	ns	$R_L = 7.5 \Omega$
Turn-off delay time	t _{d(off)}	_	320	_	ns	
Fall time	t _f	_	120	_	ns	
Body to drain diode forward voltage	V_{DF}	_	1.0	_	V	I _F = 8 A, V _{GS} = 0
Body to drain diode reverse recovery time	t _{rr}	_	200	_	ns	$I_F = 8 \text{ A}, V_{GS} = 0$ $dIF/dt = 50 \text{ A}/\mu s$

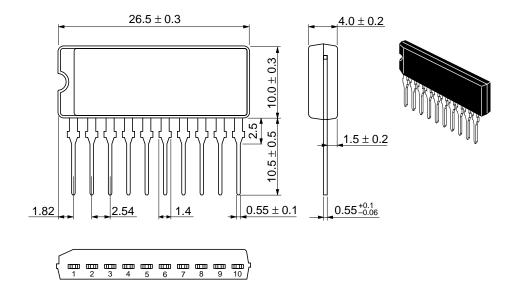
Note: 1. Pulse Test

See characteristic curves of 2SK1302

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Unit: mm



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